

Electronic Patent Application Fee Transmittal

| Application Number: | 10826985 | | | |
|--|---|-----------------|---------------|-----------------------------|
| Filing Date: | 19-Apr-2004 | | | |
| Title of Invention: | Methods for forming protective layers on semiconductor device components so as to reduce or eliminate the occurrence of delamination thereof and cracking therein | | | |
| First Named Inventor/Applicant Name: | Shijian Luo | | | |
| Filer: | Brick Glenn Power | | | |
| Attorney Docket Number: | 2269-5565.1US (02-1124.01) | | | |
| Filed as Large Entity | | | | |
| Utility Filing Fees | | | | |
| Description | Fee Code | Quantity | Amount | Sub-Total in USD(\$) |
| Basic Filing: | | | | |
| Pages: | | | | |
| Claims: | | | | |
| Miscellaneous-Filing: | | | | |
| Petition: | | | | |
| Patent-Appeals-and-Interference: | | | | |
| Notice of appeal | 1401 | 1 | 510 | 510 |
| Post-Allowance-and-Post-Issuance: | | | | |
| Extension-of-Time: | | | | |

| Description | Fee Code | Quantity | Amount | Sub-Total in USD(\$) |
|--------------------------|----------|----------|--------|----------------------|
| Miscellaneous: | | | | |
| Total in USD (\$) | | | | 510 |